

Product End-of-Life Disassembly Instructions

Product Type/ Category: Desktop

Product Name / Model: TECHCOMPUTER / TC SFF

1. **Purpose:** This document is intended for use by End-Of-Life (EOL) recyclers, reusers or treatment facilities. It provides the basic instructions for the disassembly of products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EU, Waste Electrical and Electronic Equipment (WEEE).

2. **Compliance:** EU directive 2012/19/EU WEEE - Annex VII materials.

EU directive 2012/19/EU WEEE - Annex VII materials		
Contain (Yes/No)	Component	Quantity
Polychlorinated biphenyls (PCB) containing capacitors in accordance with Council Directive 96/59/EC of 16 September 1996 on the disposal of polychlorinated biphenyls and polychlorinated terphenyls (PCB/PCT)		
No		
Mercury containing components, such as switches or backlighting lamps		
No		
Batteries		
Yes	Button Cell	1
Printed circuit boards of mobile phones generally, and of other devices if the surface of the printed circuit board is greater than 10 square centimetres		
Yes	Main Printed Circuit Board RAM Printed Circuit Board SSD Printed Circuit Board Power Supply Printed Circuit Board	4
Toner cartridges, liquid and paste, as well as colour toner		
No		
Plastic containing brominated flame retardants		
No		
Asbestos waste and components which contain asbestos		

No		
Cathode ray tubes		
No		
Chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)		
No		
Gas discharge lamps		
No		
Liquid crystal displays (together with their casing where appropriate) of a surface greater than 100 square centimetres and all those back-lighted with gas discharge lamps		
No		
External electric cables		
Yes	Power Cord	1
Components containing refractory ceramic fibres as described in Commission Directive 97/69/EC of 5 December 1997 adapting to technical progress for the 23rd time Council Directive 67/548/EEC on the approximation of the laws, regulations and administrative provisions relating to the classification, packaging and labelling of dangerous substances		
No		
Components containing radioactive substances with the exception of components that are below the exemption thresholds set in Article 3 of and Annex I to Council Directive 96/29/Euratom of 13 May 1996 laying down basic safety standards for the protection of the health of workers and the general public against the dangers arising from ionizing radiation		
No		
Electrolyte capacitors containing substances of concern (height > 25 mm, diameter > 25 mm or proportionately similar volume)		
Yes	PSU	1

3. **Tools required:** List of the tools that would usually be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Type/size	Quantity
Screwdriver	PH1	1
Screwdriver	PH2	1
Screwdriver	Slotted	1

4. **Product Disassembly Process:** List of the steps that should usually be followed to remove components and materials requiring selective treatment.

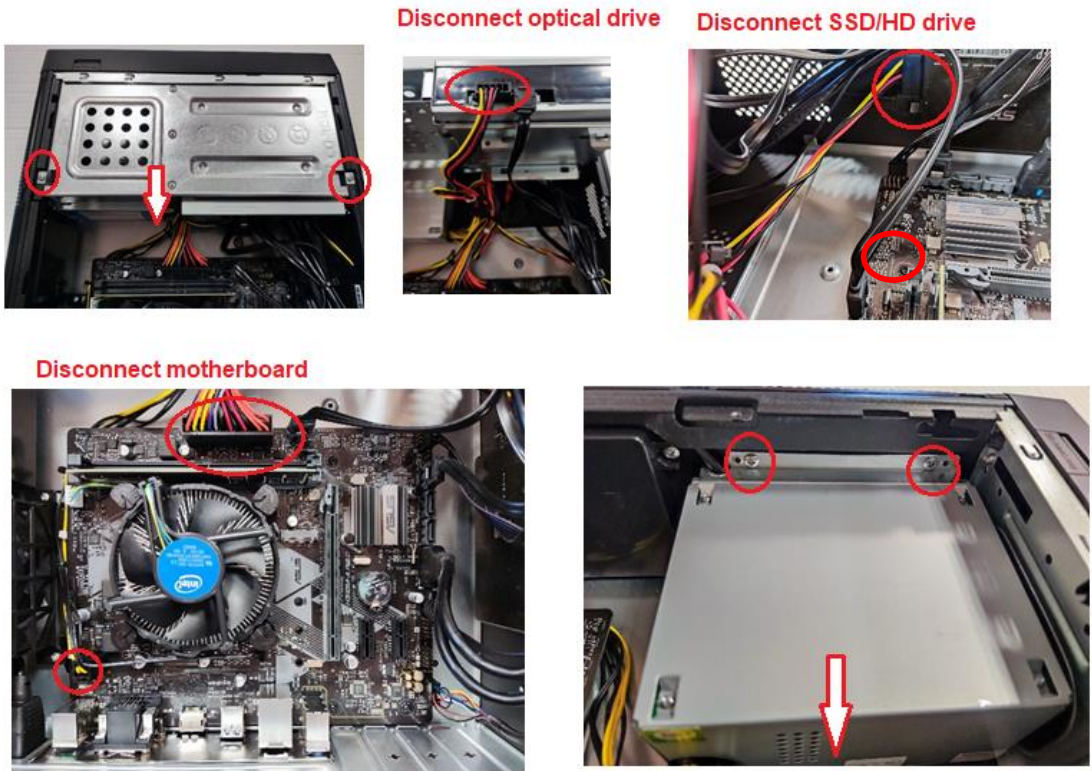
Step	Activity	Description
1	Remove Top Case	Remove the screw and remove the top case
2	Remove Power Supply Unit	Remove the screws of HDD/SDD/ODD tray and remove the tray. Disconnect all power cables. Remove the screws of power supply unit
3	Remove PSU PCB & Capacitor	Remove all screws. Remove PSU PCB and remove the Capacitor
4	Remove SSD & RAM	Remove the screw and remove the SSD. Press the latch and remove RAM
5	Remove Main PCB Connectors	Disconnect all connectors
6	Remove Main PCB	Remove all screws and remove main PCB
7	Remove CPU	Remove all fan screws and remove cooler fan. Open CPU door and remove CPU
8	Remove Bottom Cell	Remove Bottom Cell (Li-Ion)

5. **Product Disassembly Graphic Process:** If the disassembly process is complex, follow the illustrations below to identify the components contained in the product that require selective treatment.

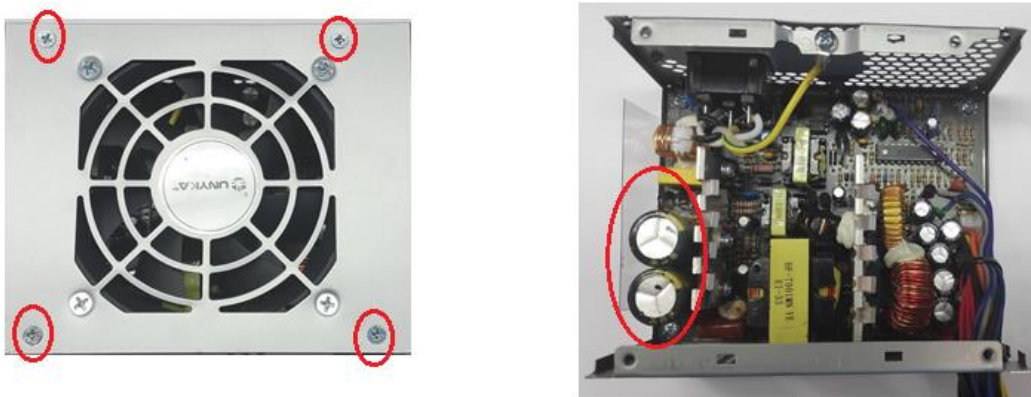
Step 1. Remove Top Case



Step 2. Remove Power Supply Unit



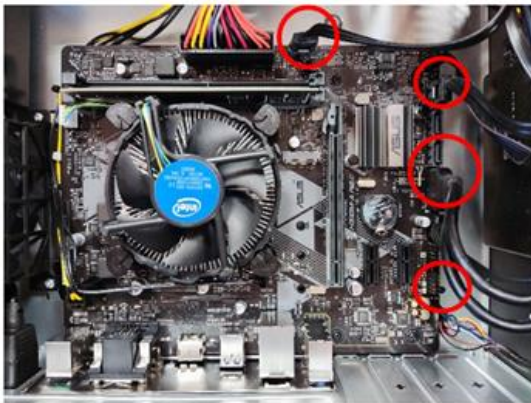
Step 3. Remove PSU PCB and capacitor



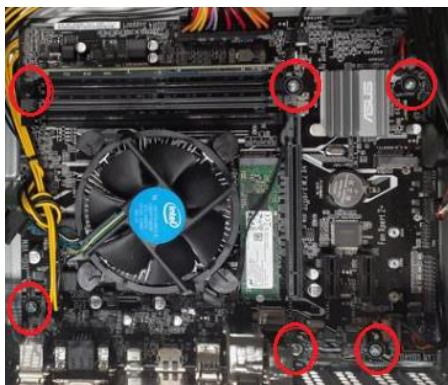
Step 4. Remove SSD M.2 & RAM



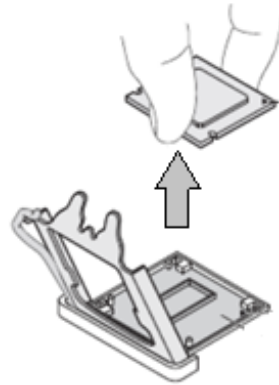
Step 5. Remove Main PCB connectors



Step 6. Remove Main PCB



Step 7. Remove CPU



Step 8. Remove Bottom Cell (Li-Ion)

